# NiO-Ti nanocomposites for contact electrification and energy harvesting: Experimental and DFT+U studies

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Figure S1: Milling time-dependent mechanochemical reduction of NiO by a reactive Ti to form an *in-situ* NiO-Ni-TiO<sub>2</sub> nanocomposite (a); The enlarged version of the peaks within  $2\theta$  = 40-48° showing the formation of Ni at the critical activation time of 10 h.



Figure S2: Bright-field TEM images and selected area electron diffraction patterns of NiO-Ti powders prepared at different milling periods with (a) Bulk NiO; (b)  $t_{mill} = 5$  h; (c)  $t_{mill} = 10$  h; (d)  $t_{mill} = 30$  h.



Figure S3: (a) Milling time-dependent magnetic hysteresis (*M-H*) loops measured at room temperature; (b) Percentage of Ni estimated for the NiO-Ti powders at different milling periods.



Figure S4: AFM (surface roughness) and KPFM (surface potential) features of the NiO-Ni-TiO<sub>2</sub> nanocomposite.



Figure S5: Voltage and current of the TENG based on NiO and Kapton triboelectric layers.



Figure S6: Electrical current output for single unit TENG and two units of TENG (multi) connected in parallel connection.



Figure S7: Surface micrographs of bare copper and NiO-Ni-TiO<sub>2</sub> particles attached to copper electrode.

SI.	Device structure	Working Mode	Active Materials	Voltage (V)	Current (µA)	Ref.
1	Spring Type Contact Separation	TENG	Kapton/ZnO	57	1.21	1
2	Spring Type Contact Separation	TENG- PENG hybrid	Ti <sub>0.8</sub> O <sub>2</sub> -Ag co- doped BaTiO <sub>3</sub> / PDMS	150	0.32	2
3	Flapper type single electrode mode	TENG	ZnO nanorods/PDMS	5.34	0.181	3
4	Vertical contact mode	TENG	Ba <sub>3</sub> Fe <sub>2</sub> TeO <sub>9</sub> / Kapton	88	2.69	4
5	Square shape vertical contact separation	TENG	Al <sub>2</sub> O <sub>3</sub> -PDMS	34	1.77	5
6	Square shape vertical contact separation	TENG	SiO <sub>2</sub> -TiO <sub>2</sub>	0.2	-	
7	Square shape vertical contact separation	TENG	TiO <sub>2</sub> -HfO <sub>2</sub>	0.2	-	6
8	Square shape vertical contact separation	TENG	Al <sub>2</sub> O <sub>3</sub> -HfO <sub>2</sub>	0.25	-	
9	Vertical contact separation	TENG	TiO <sub>2</sub> -Natural rubber	45-78	4.5-7.0	7
10	Spring Type contact separation (2 cm × 2 cm)	TENG	NiO-Mg/ Kapton	35	0.13	
11	Spring Type contact separation (2 cm × 2 cm ) two units in parallel	TENG	NiO-Mg/ Kapton	35	0.49	8
12	Spring Type contact separation (3.5 cm × 3.5 cm)	TENG	NiO-Mg/ Kapton	80	1.0	
13	Eye-shaped vertical contact separation	TENG	NiO-Ni-TiO <sub>2</sub> / Kapton	60	0.6	This work

 Table S1: Comparison of different metal-oxide based TENG with present work.

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